



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10B103KB8NNWC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 10nF, 50V, ±10%, X7R, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>B</u> <u>103</u> <u>K</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>W</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor			
2	Size	0603 (inch code)	L: 1.6 ± 0.1 mm	W: $0.8 \pm 0.1$	mm
3	Dielectric	X7R	8 Inner electro	ode Ni	
4	Capacitance	<b>10</b> nF	Termination	Cu	
⑤	Capacitance	±10 %	Plating	Sn 100%	(Pb Free)
	tolerance		Product	Normal	
6	Rated Voltage	50 V	10 Special	Product for N	letwork application
7	Thickness	0.8 ± 0.1 mm	① Packaging	Cardboard T	ype, 7" reel

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition			
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms			
Tan δ (DF)	0.025 max.				
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.			
Resistance	Whichever is Smaller				
Appearance	No abnormal exterior appearance	Microscope (×10)			
Withstanding	No dielectric breakdown or	250% of the rated voltage			
Voltage	mechanical breakdown				
Temperature X7R					
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)				
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.			
of Termination	terminal electrode				
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)			
		with 1.0mm/sec.			
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder			
	is to be soldered newly	245±5℃, 3±0.3sec.			
		(preheating : 80~120 ℃ for 10~30sec.)			
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5°C, 10±1sec.			
Soldering heat	Tan δ, IR : initial spec.				

	Performance	Test condition	
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm	
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)	
		2hours × 3 direction (x, y, z)	
Moisture Capacitance change: within ±12.5%		With rated voltage	
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs	
	IR: 500Mohm or 25Mohm · μF		
	Whichever is Smaller		
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage	
Resistance	Tan δ : 0.05 max	Max. operating temperature	
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F		
	Whichever is Smaller	1000+48/-0hrs	
Temperature	Capacitance change: within ±7.5%	1 cycle condition	
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C	
		→ Max. operating temperature → 25°C	
		5 cycle test	

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.